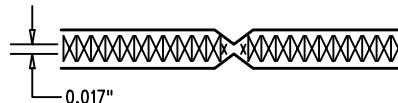




1. MATERIAL: FR4 OR EQUIVALENT EPOXY 2 OZ. COPPER CLAD.
THICKNESS .062" +/-.006 TOTAL OF 2 LAYERS.
2. FINISH: ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE.
ELECTRODEPOSITED TIN-LEAD COMPOSITION.
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK: BOTH SIDES USING GREEN PC-401 OR EQUIVALENT.
4. SILKSCREEN: USING WHITE NON-CONDUCTIVE EPOXY INK.
5. ALL DIMENSIONS ARE INCHES.
6. SCORING:



SIZE	QTY	SYM	PLTD
20	20	+	PLTD
45	3	X	PLTD
72	2	Y	NPLTD
95	9	Z	PLTD

Fabrication Drawing